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A3G4250D

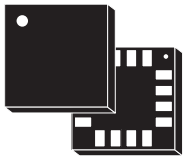
MEMS motion sensor: 3-axis digital output gyroscope

Features

- Wide supply voltage: 2.4 V to 3.6 V
- ±245 dps full scale
- I^2C/SPI digital output interface
- 16-bit rate value data output
- 8-bit temperature data output
- Two digital output lines (interrupt and data ready)
- Integrated low and high-pass filters with user-selectable bandwidth
- Ultra-stable over temperature and time
- Low-voltage-compatible IOs (1.8 V)
- Embedded power-down and sleep mode
- Embedded temperature sensor
- Embedded FIFO
- High shock survivability
- Extended operating temperature range (-40 °C to +85 °C)
- ECOPACK® RoHS and “Green” compliant
- AEC-Q100 qualification

Applications

- In-dash car navigation
- Telematics, e-Tolling
- Motion control with MMI (man-machine interface)
- Appliances and robotics



LGA-16 (4x4x1.1 mm^3)

Description

The A3G4250D is a low-power 3-axis angular rate sensor able to provide unprecedented stability at zero rate level and sensitivity over temperature and time. It includes a sensing element and an IC interface capable of providing the measured angular rate to the external world through a standard SPI digital interface. An I^2C-compatible interface is also available.

The sensing element is manufactured using a dedicated micro-machining process developed by STMicroelectronics to produce inertial sensors and actuators on silicon wafers.

The IC interface is manufactured using a CMOS process that allows a high level of integration to design a dedicated circuit which is trimmed to better match the sensing element characteristics.

The A3G4250D has a full scale of ±245 dps and is capable of measuring rates with a user-selectable bandwidth.

The A3G4250D is available in a plastic land grid array (LGA) package and can operate within a temperature range of -40 °C to +85 °C.

Table 1. Device summary

Order code	Temperature range (°C)	Package	Packing
A3G4250D	-40 to +85	LGA-16 (4x4x1.1 mm^3)	Tray
A3G4250DTR	-40 to +85	LGA-16 (4x4x1.1 mm^3)	Tape and reel

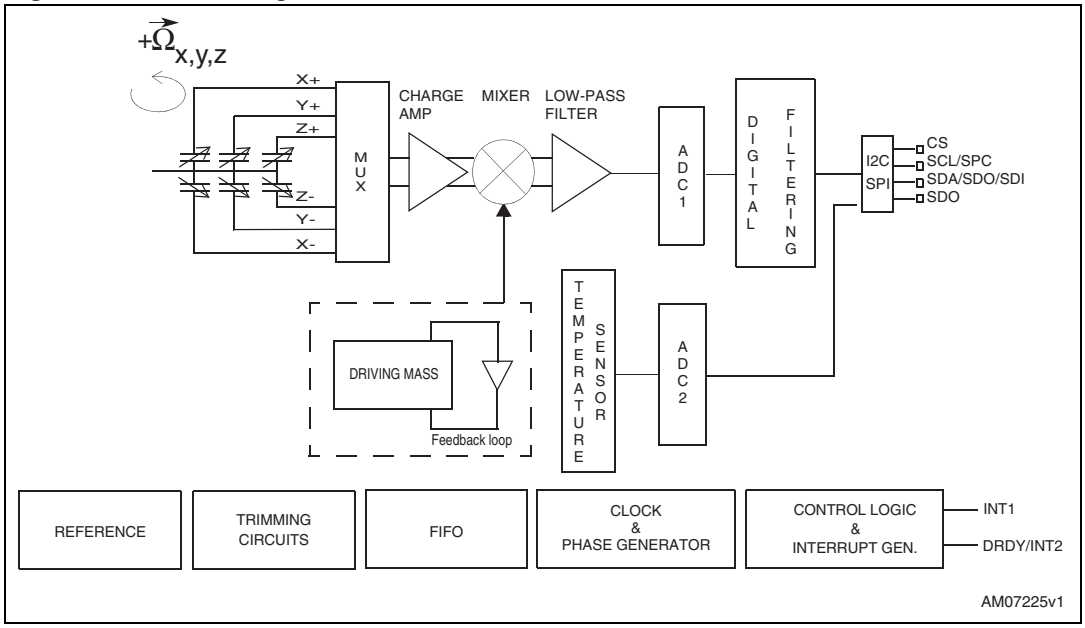
Contents

List of tables

List of figures

1 Block diagram and pin description

Figure 1. Block diagram



The vibration of the structure is maintained by drive circuitry in a feedback loop. The sensing signal is filtered and appears as a digital signal at the output.

1.1 Pin description

Figure 2. Pin connection

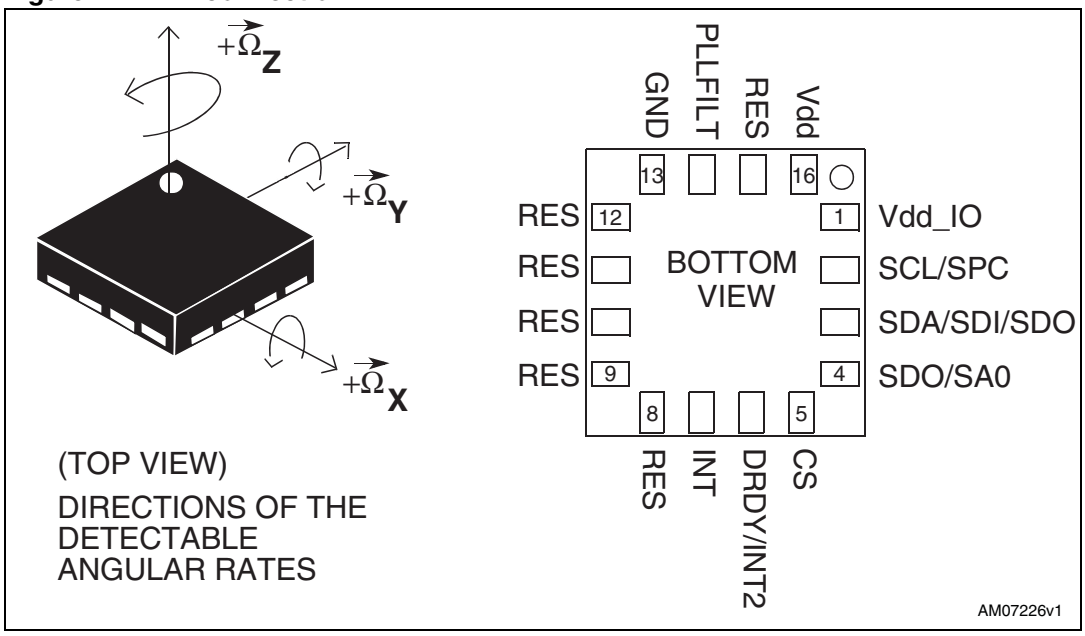
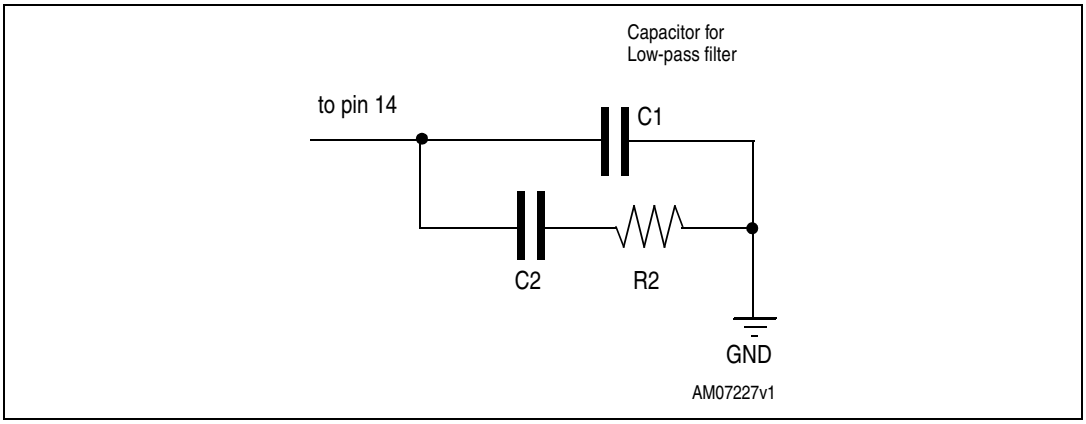


Table 2. Pin description

Pin#	Name	Function
1	Vdd_IO	Power supply for I/O pins
2	SCL SPC	I^2C serial clock (SCL) SPI serial port clock (SPC)
3	SDA SDI SDO	I^2C serial data (SDA) SPI serial data input (SDI) 3-wire interface serial data output (SDO)
4	SDO SA0	SPI serial data output (SDO) I^2C least significant bit of the device address (SA0)
5	CS	SPI enable I^2C/SPI mode selection (1: SPI idle mode / I^2C communication enabled; 0: SPI communication mode / I^2C disabled)
6	DRDY/INT2	Data ready/FIFO interrupt
7	INT1	Programmable interrupt
8	Reserved	Connect to GND
9	Reserved	Connect to GND
10	Reserved	Connect to GND
11	Reserved	Connect to GND
12	Reserved	Connect to GND
13	GND	0 V supply
14	PLLFILT	Phase-locked loop filter (see *Figure 3*)
15	Reserved	Connect to Vdd
16	Vdd	Power supply

Figure 3. A3G4250D external low-pass filter values(a)



a. Pin 14 PLLFILT maximum voltage level is equal to Vdd.

Table 3. Filter values

Parameter	Typical value
C1	10 nF
C2	470 nF
R2	10 kΩ

2 Mechanical and electrical characteristics

2.1 Mechanical characteristics

@ Vdd = 3.0 V, T = -40... +85 °C, unless otherwise noted[b].

Table 4. Mechanical characteristics

Symbol	Parameter	Test condition	Min.	Typ.(1)	Max.	Unit
FS	Measurement range(2)			±245		dps
So	Sensitivity(3)		7.4	8.75	10.1	mdps/digit
SoDr	Sensitivity change vs. temperature			±2		%
DVoff	Digital zero-rate level(3)		-25		+25	dps
OffDr	Zero-rate level change vs. temperature			±0.03		dps/°C
NL	Non linearity(2)	Best fit straight line	-5	0.2	+5	% FS
DST	Self-test output change		55	130	245	dps
Rn	Rate noise density	BW = 50 Hz		0.03	0.15	dps/ sqrt(Hz)
ODR	Digital output data rate		89/176/ 357/714	105/208/ 420/840	121/239/ 483/966	Hz
Top	Operating temperature range		-40		+85	°C

1. Typical specifications are not guaranteed; typical values at +25 °C.
2. Guaranteed by design.
3. Across temperature and after MSL3 preconditioning.

b. The product is factory calibrated at 3.0 V. The operational power supply range is specified in *Table 5*.

2.2 Electrical characteristics

@ Vdd = 3.0 V, T = -40... +85 °C, unless otherwise noted[c].

Table 5. Electrical characteristics

Symbol	Parameter	Test condition	Min.	Typ.[1]	Max.	Unit
Vdd	Supply voltage		2.4	3.0	3.6	V
Vdd_IO	I/O pins supply voltage[2]		1.71		Vdd+0.1	V
Idd	Supply current		4.8	6.1	7.0	mA
IddSL	Supply current in sleep mode[3]	Selectable by digital interface		1.5		mA
IddPdn	Supply current in power-down mode[4]	Selectable by digital interface		5	10	µA
Top	Operating temperature range		-40		+85	°C

1. Typical specifications are not guaranteed; typical values at +25 °C.
2. It is possible to remove Vdd maintaining Vdd_IO without blocking the communication busses, in this condition the measurement chain is powered off.
3. Sleep mode introduces a faster turn-on time compared to power-down mode.
4. Verified at wafer level.

2.3 Temperature sensor characteristics

@ Vdd = 3.0 V, T = 25 °C, unless otherwise noted[d].

Table 6. Temp. sensor characteristics

Symbol	Parameter	Test condition	Min.	Typ.[1]	Max.	Unit
TSDr	Temperature sensor output change vs. temperature	-		-1		°C/digit
TODR	Temperature refresh rate			1		Hz
Top	Operating temperature range		-40		+85	°C

1. Typical specifications are not guaranteed; typical values at +25 °C.

c. The product is factory calibrated at 3.0 V.

d. The product is factory calibrated at 3.0 V.

2.4 Communication interface characteristics

2.4.1 SPI - serial peripheral interface

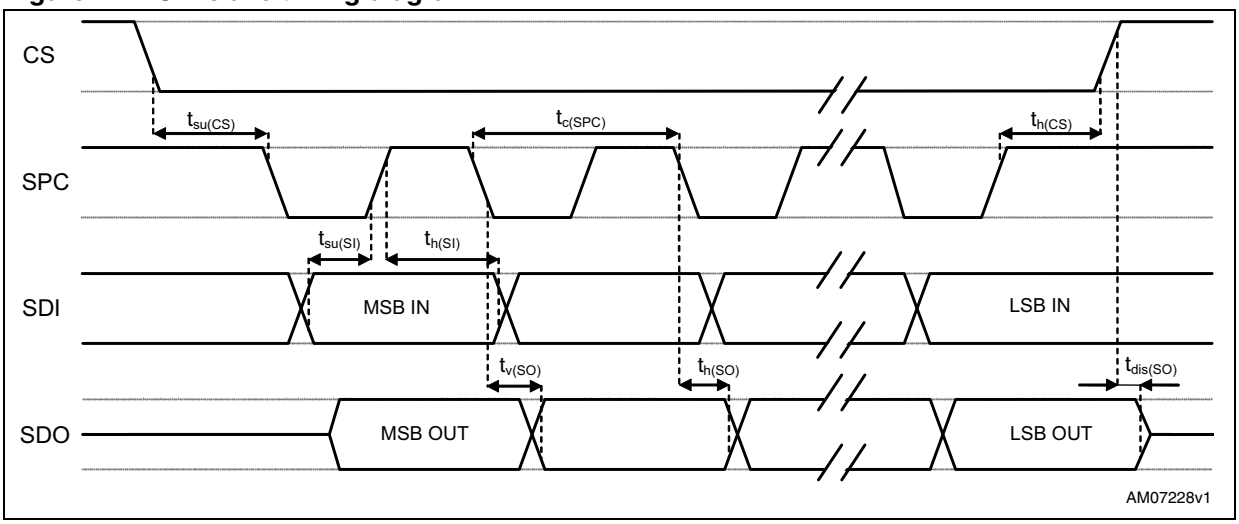
Subject to general operating conditions for Vdd and Top.

Table 7. SPI slave timing values

Symbol	Parameter	Value(1)		Unit
		Min.	Max.	
tc(SPC)	SPI clock cycle	100		ns
fc(SPC)	SPI clock frequency		10	MHz
tsu(CS)	CS setup time	5		ns
th(CS)	CS hold time	8		
tsu(SI)	SDI input setup time	5		
th(SI)	SDI input hold time	15		
tv(SO)	SDO valid output time		50	
th(SO)	SDO output hold time	6		
tdis(SO)	SDO output disable time		50	

1. Values are guaranteed at 10 MHz clock frequency for SPI with both 4 and 3 wires, based on characterization results; not tested in production.

Figure 4. SPI slave timing diagram(e)



e. Measurement points are done at 0.2·Vdd_IO and 0.8·Vdd_IO, for both input and output ports.

2.4.2 I²C - inter IC control interface

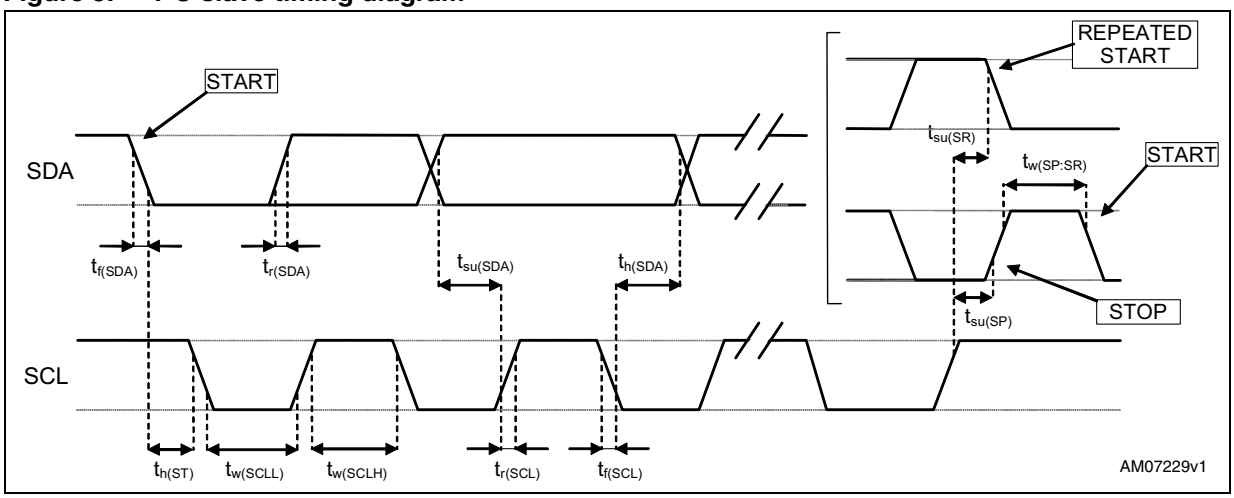
Subject to general operating conditions for Vdd and Top.

Table 8. I²C slave timing values

Symbol	Parameter	I²C standard mode(1)		I²C fast mode(1)		Unit
		Min.	Max.	Min.	Max.	
$f_{(SCL)}$	SCL clock frequency	0	100	0	400	kHz
$t_{w(SCLL)}$	SCL clock low time	4.7		1.3		µs
$t_{w(SCLH)}$	SCL clock high time	4.0		0.6		
$t_{su(SDA)}$	SDA setup time	250		100		ns
$t_{h(SDA)}$	SDA data hold time	0	3.45	0	0.9	µs
$t_{h(ST)}$	START condition hold time	4		0.6		µs
$t_{su(SR)}$	Repeated START condition setup time	4.7		0.6		
$t_{su(SP)}$	STOP condition setup time	4		0.6		
$t_{w(SP:SR)}$	Bus free time between STOP and START condition	4.7		1.3		

1. Data based on standard I²C protocol requirement; not tested in production.

Figure 5. I²C slave timing diagram(f)



f. Measurement points are done at 0.2·Vdd_IO and 0.8·Vdd_IO, for both ports.

2.5 Absolute maximum ratings

Any stress above that listed as “Absolute maximum ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device under these conditions is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

Table 9. Absolute maximum ratings

Symbol	Ratings	Maximum value	Unit
Vdd	Supply voltage	-0.3 to 4.8	V
T_{STG}	Storage temperature range	-40 to +125	°C
Sg	Acceleration *g* for 0.1 ms	10,000	*g*
ESD	Electrostatic discharge protection	2 (HBM)	kV

This is a mechanical shock sensitive device, improper handling can cause permanent damage to the part

This is an ESD sensitive device, improper handling can cause permanent damage to the part

2.6 Terminology

2.6.1 Sensitivity

An angular rate gyroscope is a device that produces a positive-going digital output for counter-clockwise rotation around the sensitive axis considered. Sensitivity describes the gain of the sensor and can be determined by applying a defined angular velocity to it. This value changes very little over temperature and time.

2.6.2 Zero-rate level

The zero-rate level describes the actual output signal if there is no angular rate present. The zero-rate level of precise MEMS sensors is, to some extent, a result of stress to the sensor and, therefore, the zero-rate level can slightly change after mounting the sensor onto a printed circuit board or after exposing it to extensive mechanical stress. This value changes very little over temperature and time.

2.6.3 Stability over temperature and time

Thanks to the unique single-driving mass approach and optimized design, ST gyroscopes are able to guarantee a perfect match of the MEMS mechanical mass and the ASIC interface, and deliver unprecedented levels of stability over temperature and time.

With the zero-rate level and sensitivity performances, up to ten times better than equivalent products currently available on the market, the A3G4250D allows the user to avoid any further compensation and calibration during production for a faster time to market, easy application implementation, higher performance, and cost saving.

2.7 Soldering information

The LGA package is compliant with the ECOPACK®, RoHS and “Green” standard.
It is qualified for soldering heat resistance according to JEDEC J-STD-020.

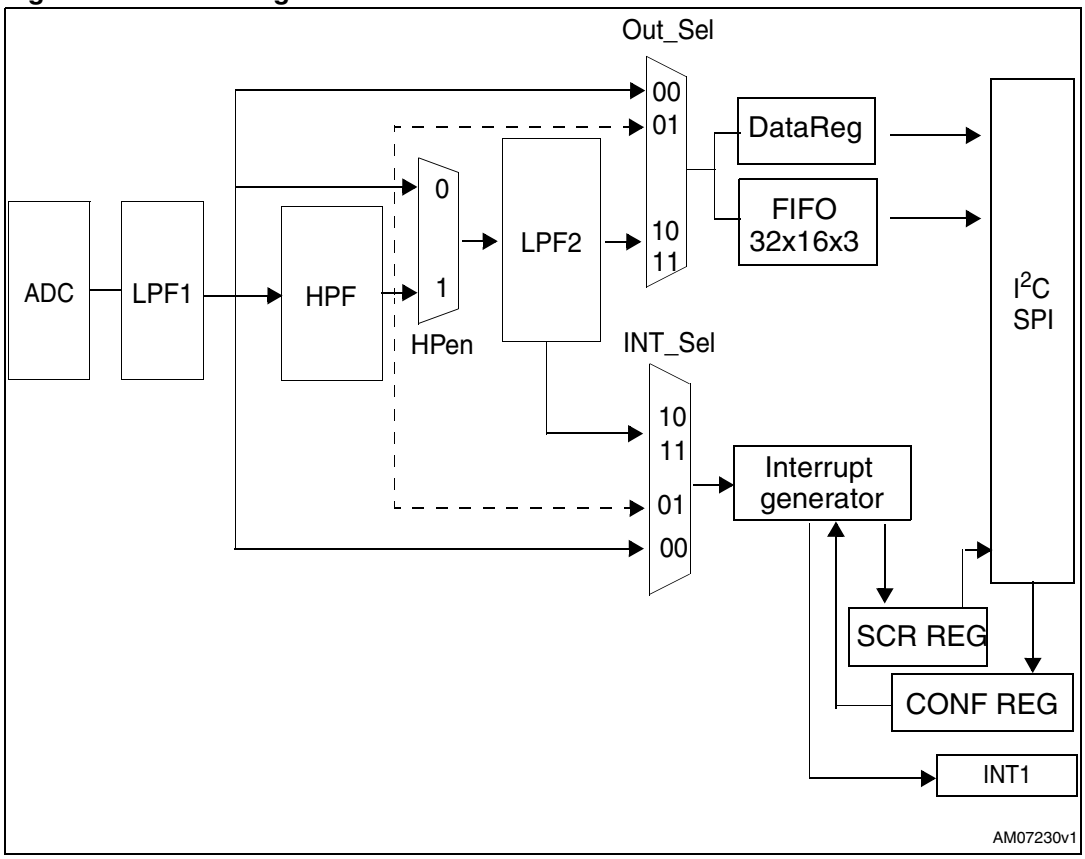
Leave “pin 1 indicator” unconnected during soldering.

Land pattern and soldering recommendations are available at www.st.com/.

3 Main digital blocks

3.1 Block diagram

Figure 6. Block diagram



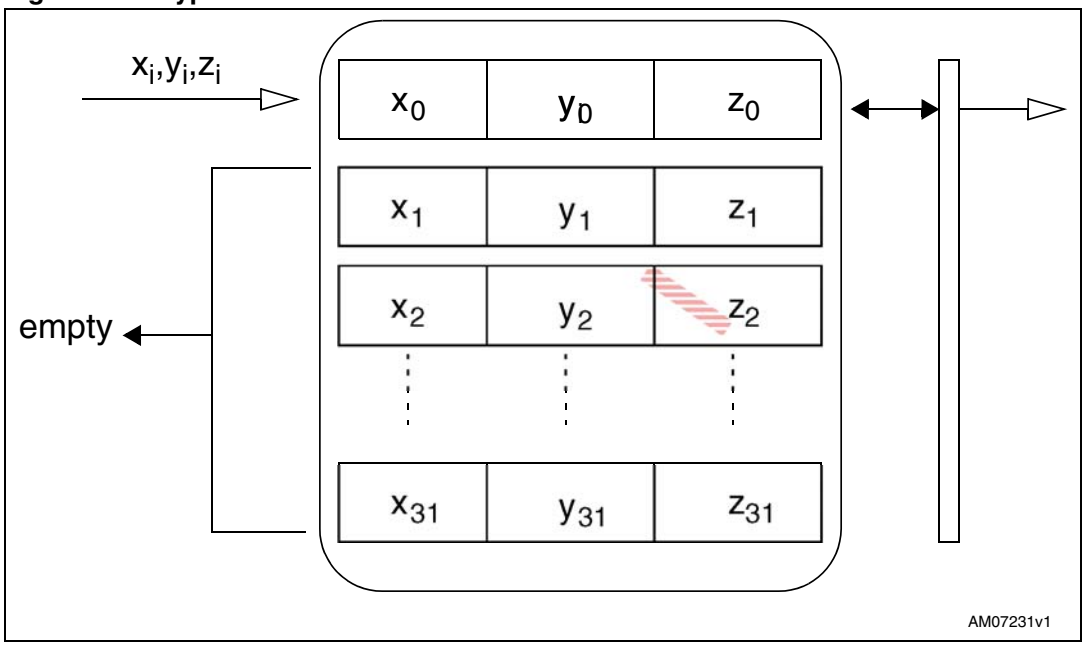
3.2 FIFO

The A3G4250D embeds a 32-slot, 16-bit data FIFO for each of the three output channels: yaw, pitch, and roll. This allows consistent power saving for the system, as the host processor does not need to continuously poll data from the sensor. Instead, it can wake up only when needed and burst the significant data out from the FIFO. This buffer can work in five different modes. Each mode is selected by the FIFO_MODE bits in FIFO_CTRL_REG. Programmable watermark level, FIFO_empty or FIFO_Full events can be enabled to generate dedicated interrupts on the DRDY/INT2 pin (configured through CTRL_REG3), and event detection information is available in FIFO_SRC_REG. The watermark level can be configured to WTM4: 0 in FIFO_CTRL_REG.

3.2.1 Bypass mode

In bypass mode, the FIFO is not operational and for this reason it remains empty. As illustrated in *Figure 7*, only the first address is used for each channel. The remaining FIFO slots are empty. When new data is available, the old data is overwritten.

Figure 7. Bypass mode

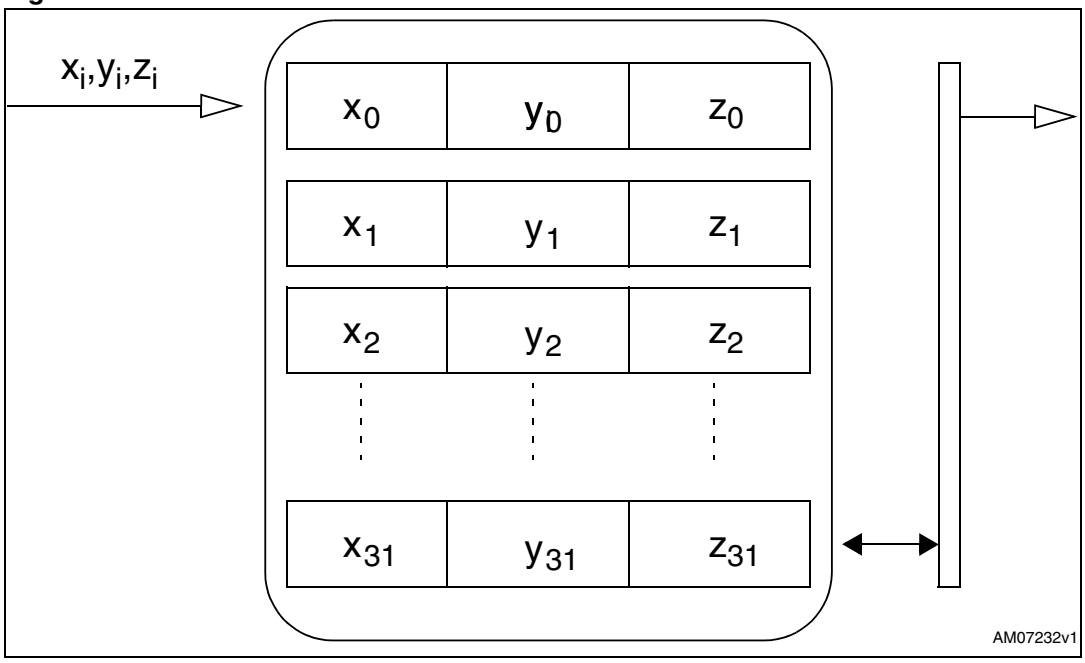


3.2.2 FIFO mode

In FIFO mode, data from the yaw, pitch, and roll channels are stored in the FIFO. A watermark interrupt can be enabled (I2_WMK bit in CTRL_REG3), which is triggered when the FIFO is filled to the level specified in the WTM 4: 0 bits of FIFO_CTRL_REG. The FIFO continues filling until it is full (32 slots of 16-bit data for yaw, pitch, and roll). When full, the FIFO stops collecting data from the input channels. To restart data collection, it is necessary to write FIFO_CTRL_REG back to bypass mode.

FIFO mode is represented in *Figure 8*.

Figure 8. FIFO mode

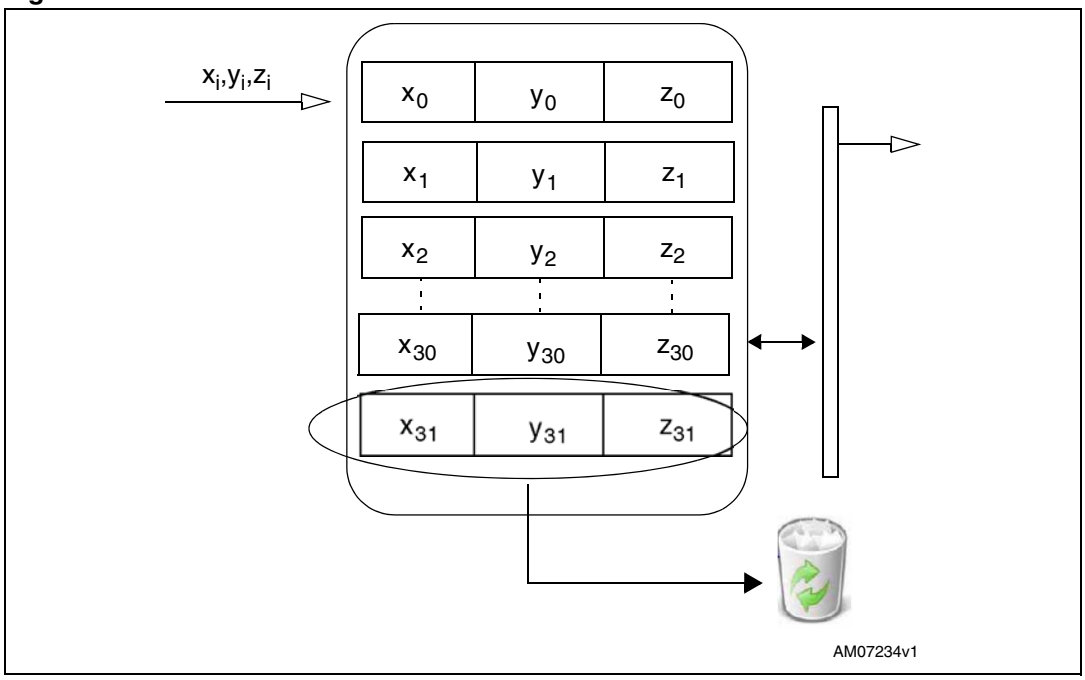


3.2.3 Stream mode

In stream mode, data from yaw, pitch, and roll measurements are stored in the FIFO. A watermark interrupt can be enabled and set as in FIFO mode. The FIFO continues filling until full (32 slots of 16-bit data for yaw, pitch, and roll). When full, the FIFO discards the older data as the new data arrives. Programmable watermark level events can be enabled to generate dedicated interrupts on the DRDY/INT2 pin (configured through CTRL_REG3).

Stream mode is represented in *Figure 9*.

Figure 9. Stream mode



3.2.4 Retrieve data from FIFO

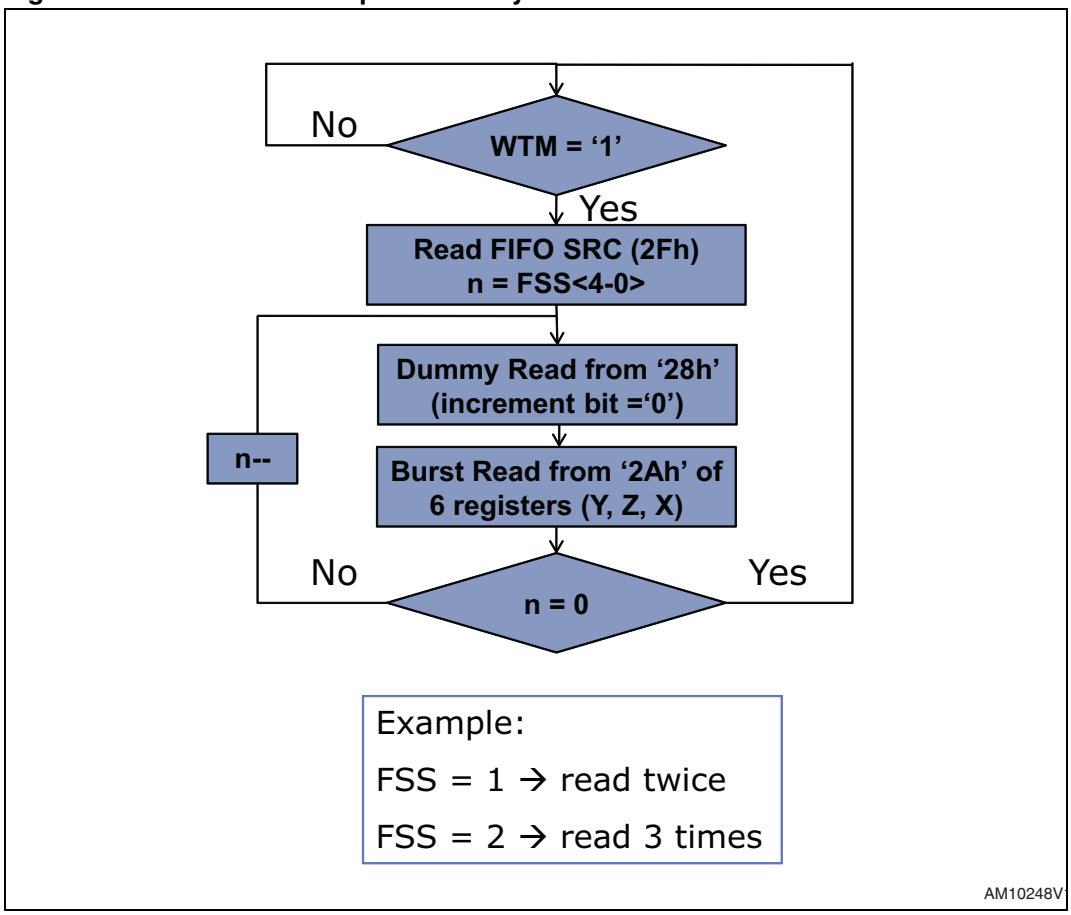
FIFO data is read through the OUT_X, OUT_Y, and OUT_Z registers. When the FIFO is in stream, trigger or FIFO mode, a read operation to the OUT_X, OUT_Y or OUT_Z registers provides the data stored in the FIFO. Each time data is read from the FIFO, the oldest pitch, roll, and yaw data are placed in the OUT_X, OUT_Y and OUT_Z registers, and both single read and read_burst (X, Y & Z with auto-incremental address) operations can be used. In read_burst mode, when data included in OUT_Z_H is read, the system again starts to read information from addr OUT_X_L.

The reading from FIFO may be executed either in synchronous or asynchronous mode. For correct data acquisition, the following points need to be followed:

1. If reading is synchronous, all data should be acquired within one ODR cycle
2. If reading is asynchronous, an appropriate FIFO access sequence must be applied:
   a) A single dummy read @ 28h (increment bit = 0) to update data out
   b) A burst read of 6 bytes from 2Ah (Y low) up to 29h:
   – Y(2A-2Bh)
   – Z(2C - 2Dh)
   – X(28-29h)

Figure 10 illustrates the correct sequence with a flow diagram:

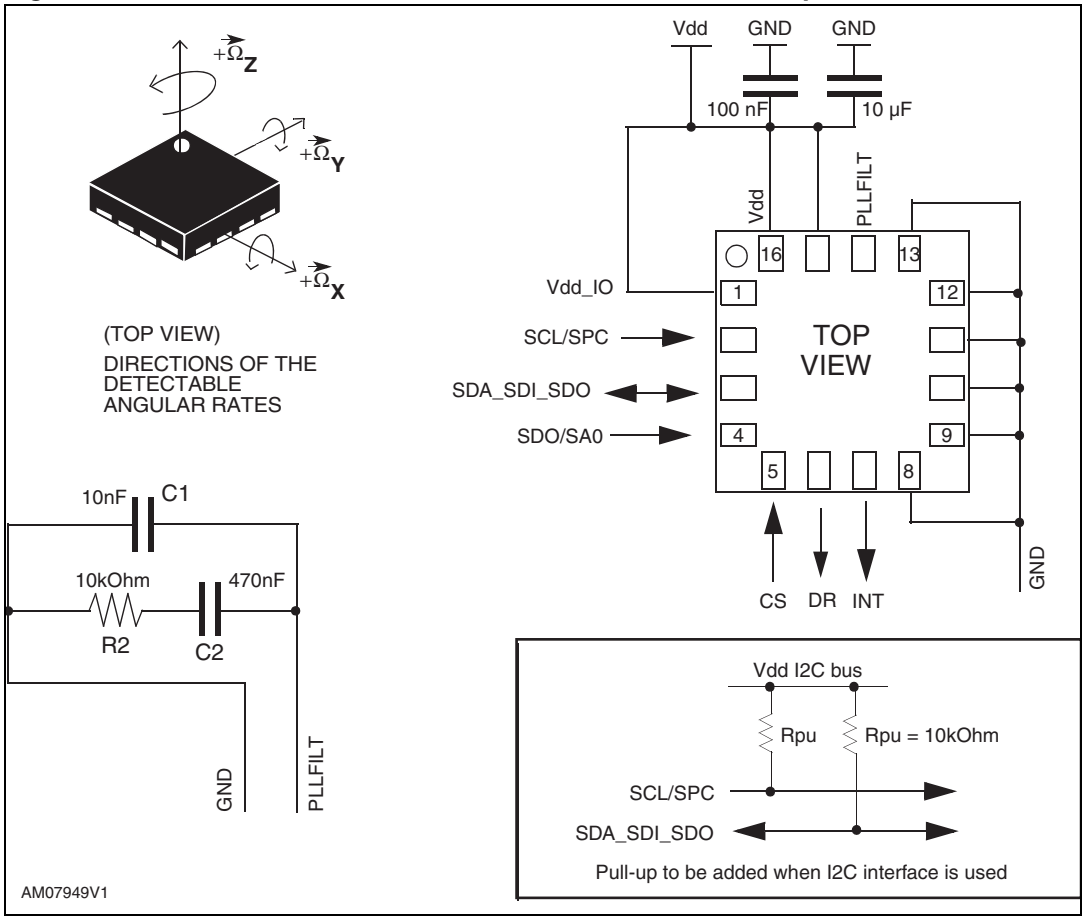
Figure 10. FIFO access sequence in asynchronous mode



If the above sequence is not followed, the acquisition from FIFO may lead to corrupted data.

4 Application hints

Figure 11. A3G4250D electrical connections and external component values



Power supply decoupling capacitors (100 nF ceramic or polyester +10 µF) should be placed as near as possible to the device (common design practice).

If Vdd and Vdd_IO are not connected together, power supply decoupling capacitors (100 nF and 10 µF between Vdd and common ground, 100 nF between Vdd_IO and common ground) should be placed as near as possible to the device (common design practice).

The A3G4250D IC includes a PLL (phase locked loop) circuit to synchronize driving and sensing interfaces. Capacitors and resistors must be added at the **PLLFILT** pin (as shown in *Figure 11*) to implement a second-order low-pass filter. *Table 10* summarizes the PLL low-pass filter component values.

Table 10. PLL low-pass filter component values

Component	Value
C1	10 nF ± 10%

Table 10. PLL low-pass filter component values

Component	Value
C2	470 nF ± 10%
R2	10 kΩ ± 10%

5 Digital interfaces

The registers embedded in the A3G4250D may be accessed through both the I^2C and SPI serial interfaces. The latter may be software-configured to operate either in 3-wire or 4-wire interface mode.

The serial interfaces are mapped onto the same pins. To select/exploit the I^2C interface, the CS line must be tied high (i.e., connected to Vdd_IO).

Table 11. Serial interface pin description

Pin name	Pin description
CS	SPI enable I^2C/SPI mode selection (1: SPI idle mode / I^2C communication enabled; 0: SPI communication mode / I^2C disabled)
SCL/SPC	I^2C serial clock (SCL) SPI serial port clock (SPC)
SDA/SDI/SDO	I^2C serial data (SDA) SPI serial data input (SDI) 3-wire interface serial data output (SDO)
SDO	SPI serial data output (SDO) I^2C least significant bit of the device address

5.1 I^2C serial interface

The A3G4250D I^2C is a bus slave. The I^2C is employed to write data to registers whose content can also be read back.

The relevant I^2C terminology is given in the table below.

Table 12. I^2C terminology

Term	Description
Transmitter	The device which sends data to the bus
Receiver	The device which receives data from the bus
Master	The device which initiates a transfer, generates clock signals and terminates a transfer
Slave	The device addressed by the master

There are two signals associated with the I^2C bus: the serial clock line (SCL) and the serial data line (SDA). The latter is a bi-directional line used for sending and receiving the data to/from the interface. Both lines must be connected to Vdd_IO through an external pull-up resistor. When the bus is free both the lines are high.

The I^2C interface is compliant with fast mode (400 kHz) I^2C standards as well as with normal mode.

5.1.1 I²C operation

The transaction on the bus is started through a START (ST) signal. A START condition is defined as a HIGH to LOW transition on the data line while the SCL line is held HIGH. After this has been transmitted by the master, the bus is considered busy. The next byte of data transmitted after the start condition contains the address of the slave in the first 7 bits and the eighth bit tells whether the master is receiving data from the slave or transmitting data to the slave. When an address is sent, each device in the system compares the first 7 bits after a start condition with its address. If they match, the device considers itself addressed by the master.

The slave address (SAD) associated with the A3G4250D is 110100xb. The SDO pin can be used to modify the least significant bit (LSb) of the device address. If the SDO pin is connected to the voltage supply, LSb is '1' (address 1101001b). Otherwise, when the SDO pin is connected to ground, the LSb value is '0' (address 1101000b). This solution permits the connection and addressing of two different gyroscopes to the same I²C bus.

Data transfer with acknowledge is mandatory. The transmitter must release the SDA line during the acknowledge pulse. The receiver must then pull the data line LOW so that it remains stable low during the HIGH period of the acknowledge clock pulse. A receiver which has been addressed is obliged to generate an acknowledge after each byte of data received.

The I²C embedded in the A3G4250D behaves like a slave device, and the following protocol must be adhered to. After the START (ST) condition, a slave address is sent. Once a slave acknowledge (SAK) has been returned, an 8-bit sub-address is transmitted. The 7 LSb represent the actual register address while the MSb enables address auto-increment. If the MSb of the SUB field is 1, the SUB (register address) is automatically incremented to allow multiple data read/write.

The slave address is completed with a read/write bit. If the bit is '1' (read), a REPEATED START (SR) condition must be issued after the two sub-address bytes; if the bit is '0' (write) the master transmits to the slave with the direction unchanged. *Table 13* describes how the SAD+read/write bit pattern is composed, listing all the possible configurations.

Table 13. SAD+read/write patterns

Command	SAD[6:1]	SAD[0] = SDO	R/W	SAD+R/W
Read	110100	0	1	11010001 (D1h)
Write	110100	0	0	11010000 (D0h)
Read	110100	1	1	11010011 (D3h)
Write	110100	1	0	11010010 (D2h)

Table 14. Transfer when master is writing one byte to slave

Master	ST	SAD + W		SUB		DATA		SP
Slave			SAK		SAK		SAK	

Table 15. Transfer when master is writing multiple bytes to slave

Master	ST	SAD + W		SUB		DATA		DATA		SP
Slave			SAK		SAK		SAK		SAK	

Table 16. Transfer when master is receiving (reading) one byte of data from slave

Master	ST	SAD + W		SUB		SR	SAD + R			NMAK	SP
Slave			SAK		SAK			SAK	DATA		

Table 17. Transfer when master is receiving (reading) multiple bytes of data from slave

Master	ST	SAD+W		SUB		SR	SAD+R			MAK		MAK		NMAK	SP
Slave			SAK		SAK			SAK	DATA		DATA		DATA		

Data are transmitted in byte format (DATA). Each data transfer contains 8 bits. The number of bytes transferred per transfer is unlimited. Data is transferred with the most significant bit (MSb) first. If a receiver cannot receive another complete byte of data until it has performed some other function, it can hold the clock line SCL LOW to force the transmitter into a wait state. Data transfer only continues when the receiver is ready for another byte and releases the data line. If a slave receiver does not acknowledge the slave address (i.e., it is not able to receive because it is performing some real-time function) the data line must be left HIGH by the slave. The master can then abort the transfer. A LOW to HIGH transition on the SDA line while the SCL line is HIGH is defined as a STOP condition. Each data transfer must be terminated by the generation of a STOP (SP) condition.

In order to read multiple bytes, it is necessary to assert the most significant bit of the sub-address field. In other words, SUB(7) must be equal to 1, while SUB(6-0) represents the address of the first register to be read.

In the presented communication format, MAK is “master acknowledge” and NMAK is “no master acknowledge”.

5.2 SPI bus interface

The SPI is a bus slave. The SPI allows writing and reading of the device registers. The serial interface interacts with the external world through 4 wires: **CS, SPC, SDI, and SDO**.